



Surge arrester

2-electrode arrester

Series/Type: A80-A75XSMD
Ordering code: B88069X6350T602
Date: 2019-04-15
Version: 07


Features

- Standard size
- Fast response time
- Very high current rating
- Stable performance over life
- Very low capacitance
- High insulation resistance
- Excellent SMD handling
- RoHS-compatible

Applications

- Tower mounted amplifier
- Consumer electronic
- Alarm systems

Electrical specifications

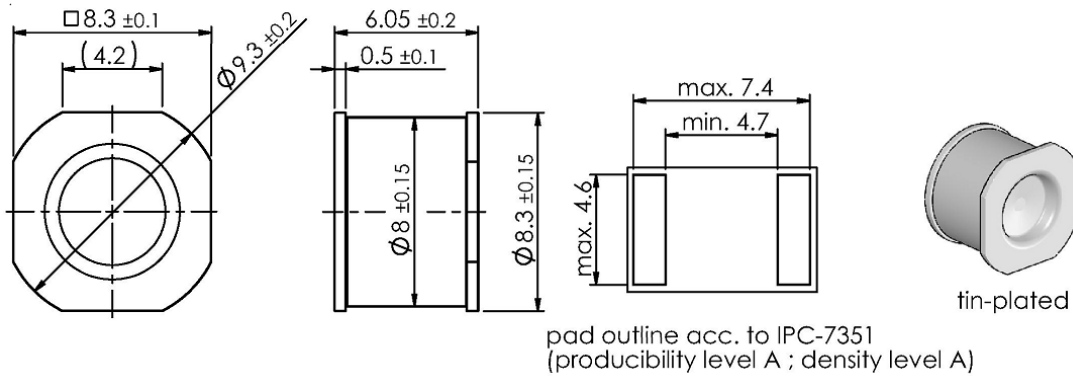
DC spark-over voltage ^{1) 2)}	75	V
Tolerance	±20	%
Min.	60	V
Max.	90	V
Impulse spark-over voltage		
at 100 V/μs - for 99% of measured values	< 350	V
- typical values of distribution	< 300	V
at 1 kV/μs - for 99% of measured values	< 650	V
- typical values of distribution	< 600	V
Service life		
10 operations 50 Hz, 1 s	20	A
1 operation 50 Hz; 0.18 s (9 cycles)	100	A
10 operations [5x (+) & 5x (-)] 8/20 μs	20	kA
1 operation 8/20 μs	25	kA
1 operation 10/350 μs	2.5	kA
300 operations 10/1000 μs	100	A
Insulation resistance at 50 V _{DC}	> 10	GΩ
Capacitance at 1 MHz	< 1.5	pF
Arc voltage at 1 A	~ 10	V
Glow to arc transition current	< 0.5	A
Glow voltage	~ 60	V
Weight	~ 1.5	g
Operation and storage temperature	-40 ... +125	°C
Climatic category (IEC 60068-1)	40/125/21	
Marking, blue negative	EPCOS 75 YY O 75 - Nominal voltage YY - Year of production O - Non radioactive	
Certification	UL 497B (E163070)	

Remarks on next page

- 1) At delivery AQL 0.65 level II, DIN ISO 2859
- 2) In ionized mode

Terms in accordance with ITU-T Rec. K.12 and IEC 61643-311

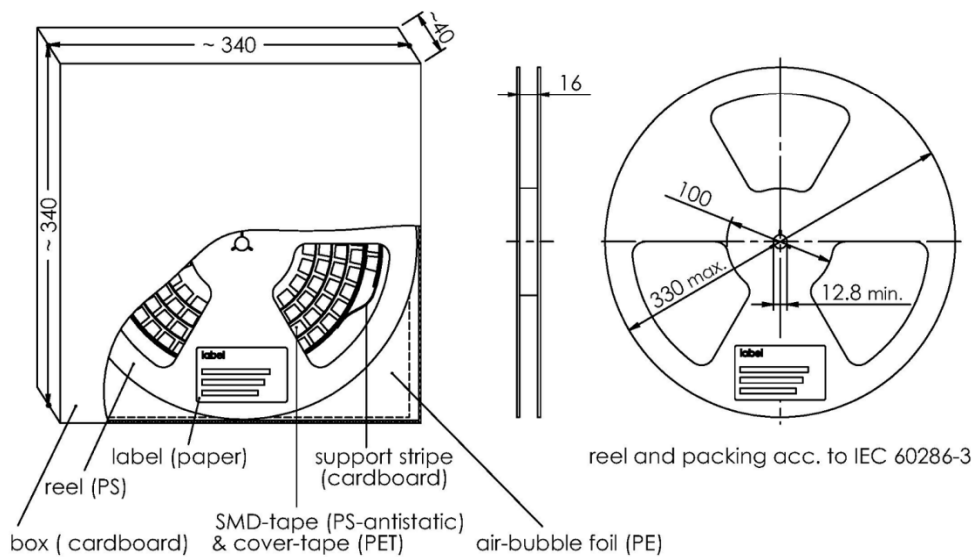
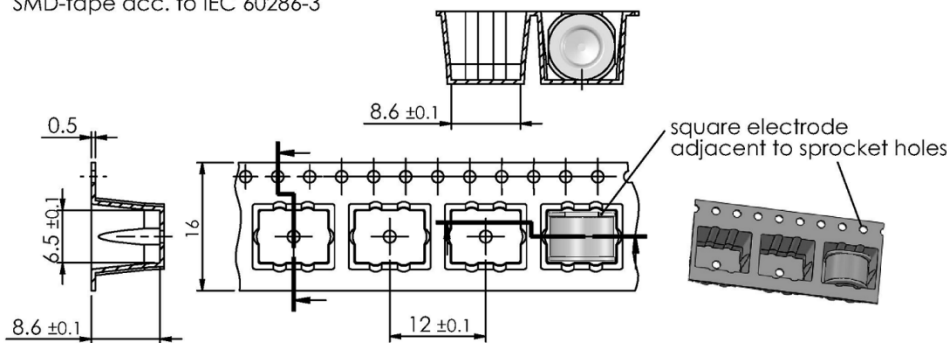
Dimensional drawing in mm



Ordering code and packing advice

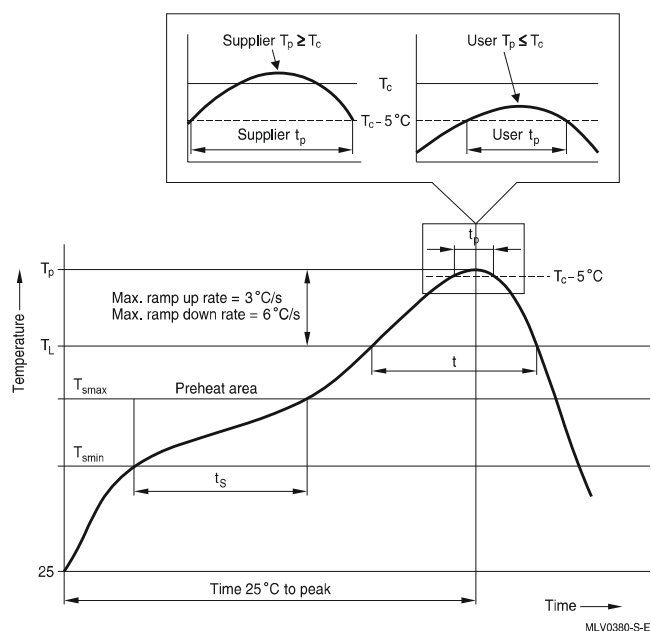
B88069X6350T602 = 600 pcs. on SMD-tape

SMD-tape acc. to IEC 60286-3



Soldering parameter

Reflow soldering



Reflow profile features		Sn- Pb eutectic assembly	Pb-free assembly
Preheat and soak - Temperature min - Temperature max - Time	T_{smin} T_{smax} t_{smin} to t_{smax}	100 °C 150 °C 60 ... 120 s	150 °C 200 °C 60 ... 180 s
Average ramp-up rate	T_{smax} to T_p	max. 3 °C/ s	max. 3 °C/ s
Liquidous temperature Time at liquidous	T_L t_L	183 °C 60 ... 150 s	217 °C 60 ... 150 s
Peak package body temperature *, Classification temperature **	T_p , T_c	220 ... 235 °C **	245 ... 260 °C **
Time (t_p) ** within 5 °C of the specified classification temperature (T_c)		20 s ***	30 s ***
Average ramp-down rate	T_p to T_{smax}	max. 6 °C/ s	max. 6 °C/ s
Time 25 °C to peak temperature		max. 6 min	max. 8 min

* = Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
 ** = For details please refer to JEDEC J-STD-020D.
 *** = Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Surface mounted components (SMD) may exhibit a temporary increase in the DC spark-over voltage after the solder reflow process. The components will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC spark-over voltage.

Cautions and warnings

- Do not operate surge arresters in power supply networks, whose maximum operating voltage exceeds the minimum spark-over voltage of the surge arresters.
- Surge arresters may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
- Surge arresters must be handled with care and must not be dropped.
- Do not continue to use damaged surge arresters.
- The shown SMD pad dimensions represent a safe way to mount the arrester and are a recommendation of the manufacturer. During the reflow process it must be assured that no solder material reduces the insulation distance between the pads below the arrester.
- SMD surge arresters should be soldered within 24 month after shipment.

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